

IN THE CLAIMS:

Please cancel claims 1, ~~3~~ and 6 without prejudice or disclaimer.

1B Pal
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Please amend claim 8 to read as follows:

C1

8. (Twice Amended) The printed circuit board unit comprising:

a printed circuit board;

an electronic component;

a solder bump interposed between the printed circuit board and the electronic component so

as to fix the electronic component to the printed circuit board; and

an interposer disposed between the printed circuit board and the electronic component so as

to define a through hole for containing the solder bump,

wherein at least an inner surface of the through hole is covered with a coating wet to a melted

state of the solder bump.

Please add new claim 16 as follows:

C2

16. (New) The printed circuit board unit according to claim 8, wherein an outer peripheral

size of the solder bump is set smaller than an inner peripheral size of the through hole.
